

PCB Specification for CX4 Mezzanine Card.

Contact: Philip Gibbs
083 324 1464
philip@ska.ac.za

Board Name: CX4 Mezzanine Card

Board Revision: 0

Release: A

PCB Details

PCB Specifications:	IPC 6012 Class 2
Finished Board Size:	110 x 90 (mm)
PCB Type:	Multilayer
Layer Count:	6
Dielectric:	-
Nominal Board Thickness:	1.622mm – 6 layer stackup
Hole Tolerance:	-
Finish:	ENIG
Soldermask:	Green
Silkscreen:	White
Minimum clearance:	6 mil

PCB Stackup

Layer	#	Copper Thickness	Dielectric	Filename
Silkscreen Top				CX4.GTO
Soldermask Top				CX4.GTS
Signal Top	1	17u	0.015mm	CX4.GTL
			0.126mm	
Power plane 1	2	35u		CX4.GP1
			0.390mm	
Internal layer 1	3	35u		CX4.GD1
			0.460mm	
Internal layer 2	4	35u		CX4.GD2
			0.390mm	
Power plane 2	5	35u		CX4.GP2
			0.126mm	
Signal Bottom	6	17u	0.015mm	CX4.GBL
Soldermask Bottom				CX4.GBS
Silkscreen Bottom				CX4.GBP

Impedance Controlled Traces

All impedance matching to +/- 10%

Microstrip:

Layers: Signal Top (#1) and Bottom (#6)
Target Impedance: 50 ohms
Trace Thickness: 8.2mil (0.208mm)